

LISTING OF CLAIMS

1. (Original) A semiconductor package comprising:

a package body, containing an integrated-circuit chip having an optical sensor, that can be fitted into an object having two parts suitable for being coupled, and in which package a board provided with electrical connection tracks is placed in a position such that the optical sensor is located facing an opening in this object;

wherein the said package body carries, on the one hand, resilient rear electrical connection leads that project from its rear face and are electrically connected to the said chip and has, on the other hand, a front bearing surface such that, when the said package body is fitted into the said object and when the said parts of this object are coupled, the front bearing surface of the said body bears on an inner surface of a part of the object and the said resilient rear leads bear resiliently on the respective electrical connection tracks of the board.

2. (Original) The package according to Claim 1, wherein the said package body and the object have respective positioning surfaces that are perpendicular to the said bearing surfaces.

3. (Original) The package according to Claim 1, wherein the object has an internal housing for housing part of the package body.

4. (Original) The package according to Claim 1, wherein the resilient rear electrical connection leads are curved.

5. (Original) The package according to Claim 1, wherein the optical sensor is located on an opposite side from the said resilient rear electrical connection leads.

6. (Original) The package according to Claim 1, wherein the internal surface of the object extends around the aforementioned opening.

7. (Original) A product, comprising:
- a first cover;
 - a printed circuit board associated with the first cover;
 - a semiconductor package having a first surface and a second surface, the package including a plurality of resilient electrical connection leads extending from the first surface, the semiconductor package positioned with its first surface adjacent the printed circuit board; and
 - a second cover mating with the first cover to define a cavity enclosing the printed circuit board and the semiconductor package, the mating of the second cover to the first cover exerting pressure against the second surface of the semiconductor package and causing the resilient electrical connection leads to bear resiliently on the printed circuit board.
8. (Original) The product as in claim 7, wherein the second cover has an internal housing for housing part of the semiconductor package.
9. (Original) The product as in claim 7, wherein the resilient electrical connection leads are curved.
10. (Original) The product as in claim 7 wherein the semiconductor package includes an optical sensor assembly associated with the second surface and wherein the second cover includes an aperture therein aligned with the optical sensor assembly when the second cover is mated with the first cover.

11. (Original) A product, comprising:
 - a split enclosure that mates together;
 - a printed circuit board located within the enclosure;
 - a semiconductor package also located within the enclosure, the package including a plurality of resilient electrical connection leads extending therefrom and positioned in contact with the printed circuit board, the leads being resiliently deformed in response to pressure exerted by mating of the split enclosure on opposite sides of the semiconductor package and printed circuit board.
12. (Original) The product as in claim 11, wherein the second cover has an internal housing for housing part of the semiconductor package.
13. (Original) The product as in claim 11, wherein the resilient electrical connection leads are curved.
14. (Original) The product as in claim 11 wherein the semiconductor package includes an optical sensor assembly and wherein the split enclosure includes an aperture therein aligned with the optical sensor assembly when the split enclosure is mated.

15. (Currently Amended) A semiconductor package comprising:
- an integrated circuit chip including an optical sensor;
 - a metal leadframe to which the integrated circuit chip is attached, the metal leadframe including a plurality of electrical connection leads made of a pressure deformable resilient material;
 - a package including an aperture aligned with the optical sensor and encapsulating the integrated circuit chip and metal leadframe, the plurality of electrical connection leads extending therefrom in a curved shape under a bottom surface thereof.

16. (Canceled).

17. (Original) A semiconductor package, comprising:
- an integrated circuit chip;
 - a plurality of electrical connection leads made of a pressure deformable resilient material, each lead having a first and second end; and
 - a package enclosing the integrated circuit chip and through which a central portion of each lead passes, the package causing the first end of each lead to resiliently contact a surface of the integrated circuit chip and the second end of each lead extending from the package in a curved shape under a bottom surface thereof.
18. (Original) The package of claim 17 wherein the integrated circuit chip includes an optical sensor and the package includes an aperture aligned with the optical sensor.